

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

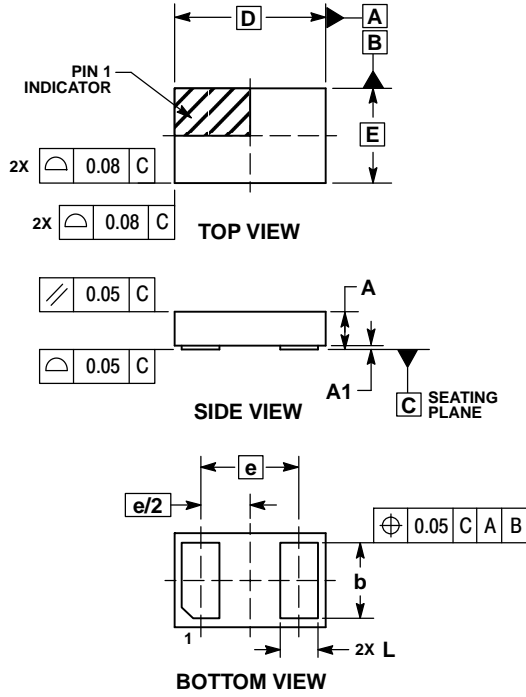
ON Semiconductor®



SCALE 4:1

UDFN2 2.0x1.25, 1.3P  
CASE 517DF  
ISSUE A

DATE 06 JUL 2016



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
b	0.95	1.05
D	2.00 BSC	
E	1.25 BSC	
e	1.30 BSC	
L	0.45	0.55

### GENERIC MARKING DIAGRAMS\*

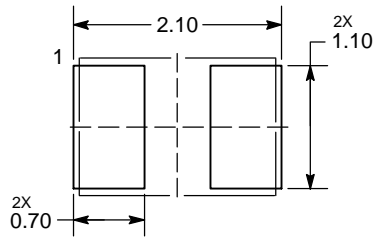


- XX = Specific Device Code  
 M = Date Code

- STYLE 1:  
 PIN 1. CATHODE (POLARITY BAND)  
 2. ANODE
- STYLE 2:  
 . NO POLARITY

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

### RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	UDFN2 2.0X1.25, 1.3P	PAGE 1 OF 2

